



Product Change Notification / JAON-19XFZX072

Date:

22-Feb-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4547 Initial Notice: Qualification of palladium coated copper (PdCu) bond wire for selected 24AA512, 24FC512 and 24LC512 device families available in 8L TSSOP package assembled at ANAP assembly site.

Affected CPNs:

[JAON-19XFZX072_Affected_CPN_02222021.pdf](#)

[JAON-19XFZX072_Affected_CPN_02222021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of palladium coated copper (PdCu) bond wire for selected 24AA512, 24FC512 and 24LC512 device families available in 8L TSSOP package assembled at ANAP assembly site.

Pre Change:

Assembled at ANAP using gold (Au) bond wire, 8290 die attach, G700A mold compound and C7025 lead frame material with matte tin lead plating, with Ag spot die attach paddle plating and 126x87 mils die attach paddle size, or Assembled at NSEB using gold (Au) bond wire, 2200D die attach, G600 mold compound and C7025 lead frame material with matte tin lead plating, with Ag spot die attach paddle plating and 126x87 mils die attach paddle size, or Assembled at MMT using gold

(Au) bond wire, 2200D die attach, G600V mold compound and C7025 lead frame material with matte tin lead plating, with Ag spot die attach paddle plating and 118x87 mils die attach paddle size.

Post Change:

Assembled at ANAP using palladium coated copper (PdCu) bond wire, 8290 die attach, G700A mold compound and C70250 lead frame material with NiPdAu lead plating, with PPF die attach paddle plating and 98x87 mils die attach paddle size.

Pre and Post Change Summary:

	Pre Change			Post Change
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand (MMT)	Amkor Technology Philippine (P1/P2), INC. / (ANAP)
Bond Wire material	Au	Au	Au	PdCu
Die Attach material	8290	2200D	2200D	8290
Mold compound material	G700A	G600	G600V	G700A
Lead frame material	C7025	C7025	C7025	C70250
Lead Plating	Matte Tin	Matte Tin	Matte Tin	NiPdAu
DAP Surface plating	Ag Spot	Ag Spot	Ag Spot	PPF
Lead frame paddle size	126x87 mils	126x87 mils	118x87 mils	98x87 mils
	See attached pre and post change comparison			

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve productivity by qualifying palladium coated copper (PdCu) bond wire at ANAP assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:May 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2021					-->	May 2021				
Workweek	06	07	08	09	10		19	20	21	22	23

Initial PCN Issue Date				X							
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 22, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-19XFZX072_Qual_Plan.pdf](#)

[PCN_JAON-19XFZX072_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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